## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

PATENT NO. : 7,061,625 B1 APPLICATION NO.: 10/672298

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DATED INVENTOR(S) : Hwang et al. Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

## In the Specification:

Column 17, line 52, insert -- In an alternative embodiment, two or more image acquisitions may be used to assist in defect detection for different applications and to minimize process noise. That is, by acquiring and storing two different images of the same portion of the wafer sample, for example at two different planes, post processing analysis, such as performed in block 340, may better discriminate between defects and pattern noise. Alternatively, two or more image sensors may be used to inspect the complex field at two different planes, for example by incorporating two sets of optics. Thus, the scope of the invention is not to be limited to a single interferometric microscope module.

Although the foregoing invention has been described in some detail for purposes of clarity of understanding, it will be apparent that certain changes and modifications may be practiced within the scope of the appended claims. It should be noted that there are many alternative ways of implementing both the process and apparatus of the present invention. Accordingly, the present embodiments are to be considered as illustrative and not restrictive, and the invention is not to be limited to the details given herein, but may be modified within the scope and equivalents of the appended claims.--

Signed and Sealed this

Twenty-seventh Day of February, 2007

JON W. DUDAS Director of the United States Patent and Trademark Office